

Fig. 1

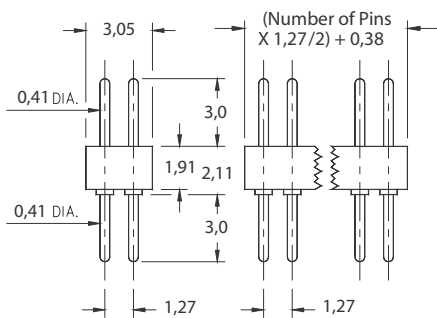


Fig. 2

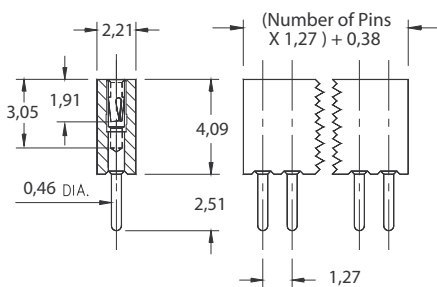


Fig. 3

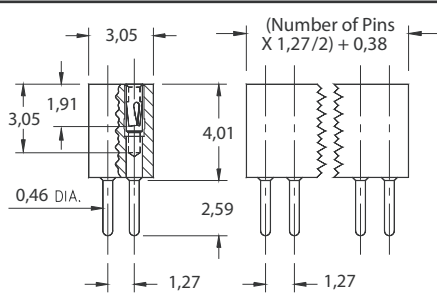


Fig. 4

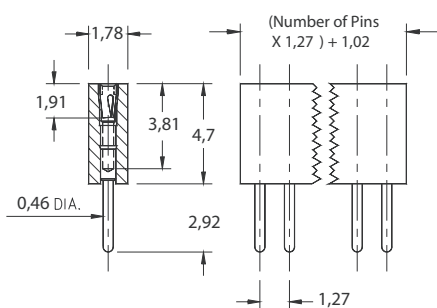
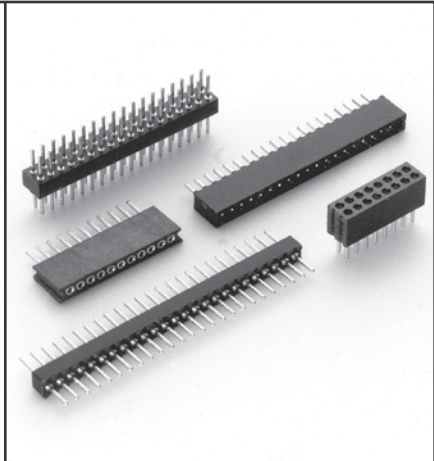


Fig. 5

- Series 850 single and double row interconnects have 1,27 pin spacing and permit board stacking as low as 6,3.
- Pin headers have 0,41 dia. pins. (MM# 4006-0 see page 166 for details).
- MM# 4890-0 and 0467 receptacles use M-M#11 Hi-Rel, 3-finger beryllium copper contacts rated at 3 amps. (#11 contact accepts pin diameters from 0,38 - 0,51)
- Insulators are high temp. thermo-plastic, suitable for all soldering operations.



Ordering Information

Fig. 1	Single Row	2,21 Profile Pin Header
	850-XX-0__-10-001000 Specify # of pins → 01-50	
Fig. 2	Double Row	1,91 Profile Pin Header
	852-XX-__-10-001000 Specify # of pins → 002-100	



*XX= Plating Code
See Below*

SPECIFY PLATING CODE XX=	10 ◇	90	40 ◇	
Pin Plating	0,25µm Au	5,08µm Sn/Pb	5,08µm Sn	

Fig. 3	Single Row	4,09 Profile Socket
	851-XX-0__-10-001000 Specify # of pins → 01-50	
Fig. 4	Double Row	4,09 Profile Socket
	853-XX-__-10-001000 Specify # of pins → 002-100	
Fig. 5	Single Row	4,7 Profile Socket
	851-XX-0__-10-002000 Specify # of pins → 01-77	



*XX= Plating Code
See Below*

SPECIFY PLATING CODE XX=	13 ◇	93	99	43 ◇	44 ◇
Sleeve (Pin)	0,25µm Au	5,08µm Sn/Pb	5,08µm Sn/Pb	5,08µm Sn	5,08µm Sn
Contact (Clip)	0,76µm Au	0,76µm Au	5,08µm Sn/Pb	0,76µm Au	5,08µm Sn